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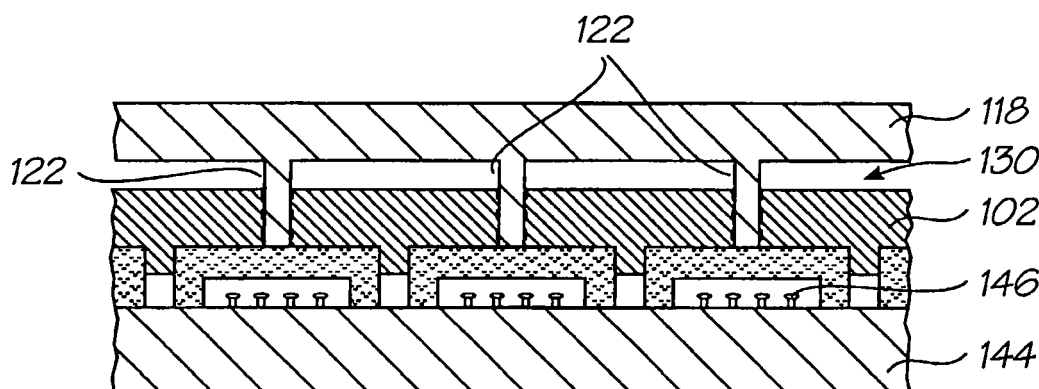
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(54) Title: **WAFER SCALE MOLDING OF PROTECTIVE CAPS**

(57) Abstract: The invention is a method of applying an array (134) of caps to a wafer (144) of semiconductor material which includes a plurality of microfabricated devices (146). The method includes applying the array (134) of first caps substantially simultaneously to one side of the wafer (144), bonding the array (134) of caps to the wafer (144) and then separating the wafer into individual packages (148).

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